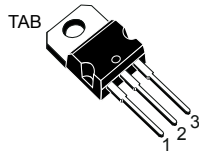
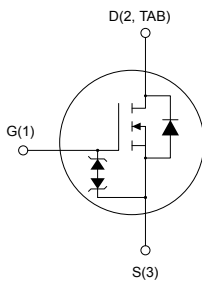


## Automotive-grade N-channel 400 V, 63 mΩ typ., 38 A MDmesh DM2 Power MOSFET in a TO-220 package



TO-220



AM15572V1\_TAB


**Product status link**
[STP45N40DM2AG](#)
**Product summary**

<b>Order code</b>	STP45N40DM2AG
<b>Marking</b>	45N40DM2
<b>Package</b>	TO-220
<b>Packing</b>	Tube

### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STP45N40DM2AG	400 V	72 mΩ	38 A

- AEC-Q101 qualified
- Fast-recovery body diode
- Extremely low gate charge and input capacitance
- Low on-resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### Applications

- Switching applications

### Description

This high-voltage N-channel Power MOSFET is part of the MDmesh DM2 fast-recovery diode series. It offers very low recovery charge (Q<sub>rr</sub>) and time (t<sub>rr</sub>) combined with low R<sub>DS(on)</sub>, rendering it suitable for the most demanding high-efficiency converters and ideal for bridge topologies and ZVS phase-shift converters.

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	400	V
$V_{GS}$	Gate-source voltage	±25	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ °C}$	38	A
	Drain current (continuous) at $T_C = 100\text{ °C}$	24	
$I_{DM}^{(1)}$	Drain current (pulsed)	152	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ °C}$	250	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	50	V/ns
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	50	
$T_{stg}$	Storage temperature range	-55 to 150	°C
$T_J$	Operating junction temperature range		

1. Pulse width is limited by safe operating area.
2.  $I_{SD} \leq 38\text{ A}$ ,  $di/dt = 800\text{ A}/\mu\text{s}$ ,  $V_{DS}(\text{peak}) < V_{(BR)DSS}$ ,  $V_{DD} = 320\text{ V}$
3.  $V_{DD} \leq 320\text{ V}$

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	0.5	°C/W
$R_{thJA}$	Thermal resistance, junction-to-ambient	62.5	

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}^{(1)}$	Avalanche current, repetitive or not repetitive	7	A
$E_{AS}^{(2)}$	Single pulse avalanche energy	1.1	J

1. Pulse width is limited by  $T_{Jmax}$ .
2. starting  $T_J = 25\text{ °C}$ ,  $I_D = I_{AR}$ ,  $V_{DD} = 50\text{ V}$

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ , $I_D = 1\text{ mA}$	400			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 400\text{ V}$			10	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 400\text{ V}$ , $T_C = 125\text{ °C}^{(1)}$			100	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 25\text{ V}$			$\pm 5$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 19\text{ A}$		63	72	m $\Omega$

1. Specified by design, not tested in production.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	2600	-	pF
$C_{oss}$	Output capacitance		-	180	-	pF
$C_{rss}$	Reverse transfer capacitance		-	3.5	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{GS} = 0\text{ V}$ , $V_{DS} = 0\text{ to }320\text{ V}$	-	300	-	pF
$R_g$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , $I_D = 0\text{ A}$	-	4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 320\text{ V}$ , $I_D = 28\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see the Figure 14. Test circuit for gate charge behavior)	-	56	-	nC
$Q_{gs}$	Gate-source charge		-	13	-	nC
$Q_{gd}$	Gate-drain charge		-	28	-	nC

1.  $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 200\text{ V}$ , $I_D = 19\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	20	-	ns
$t_r$	Rise time		-	6.7	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	68	-	ns
$t_f$	Fall time		-	9.8	-	ns

**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		38	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		152	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 38 \text{ A}$ , $V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 38 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ ,	-	95		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$	-	0.4		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	8.5		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 38 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ ,	-	185		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60 \text{ V}$ , $T_J = 150 \text{ }^\circ\text{C}$	-	1.62		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	17.5		A

1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

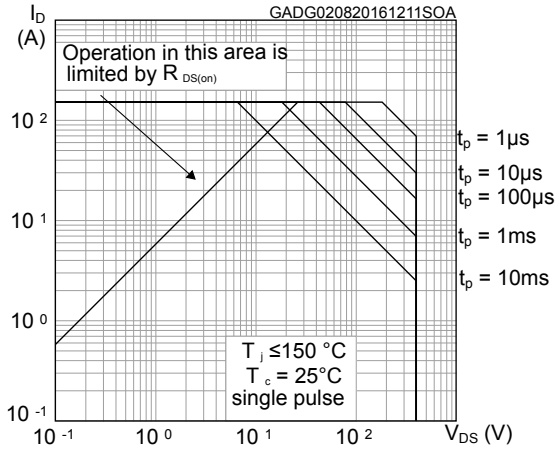


Figure 2. Normalized transient thermal impedance

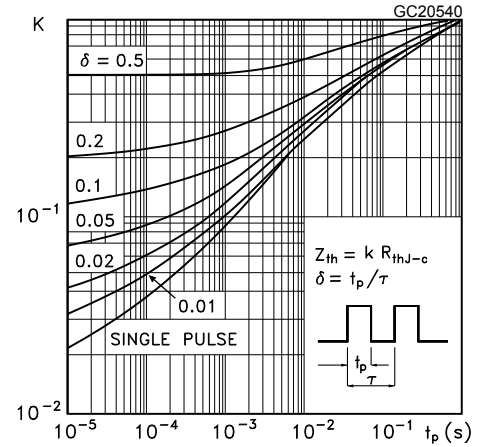


Figure 3. Typical output characteristics

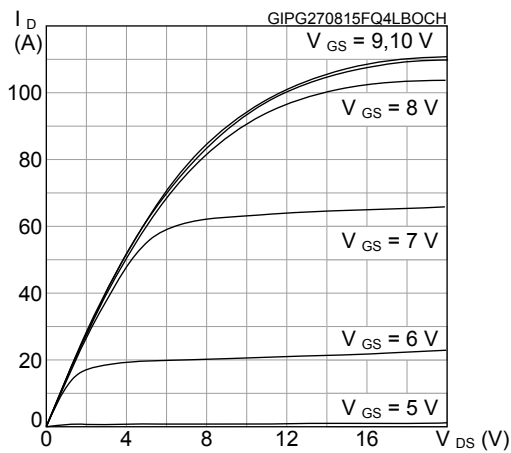


Figure 4. Typical transfer characteristics

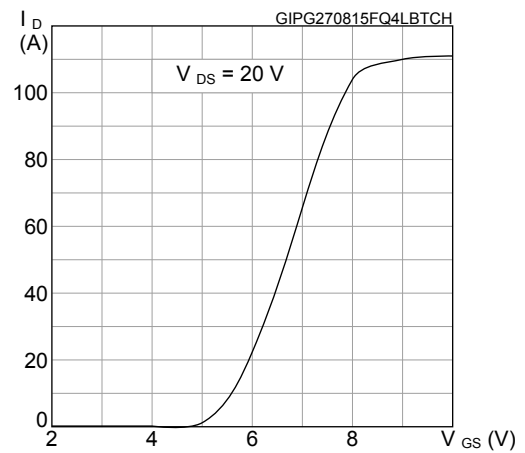


Figure 5. Typical gate charge characteristics

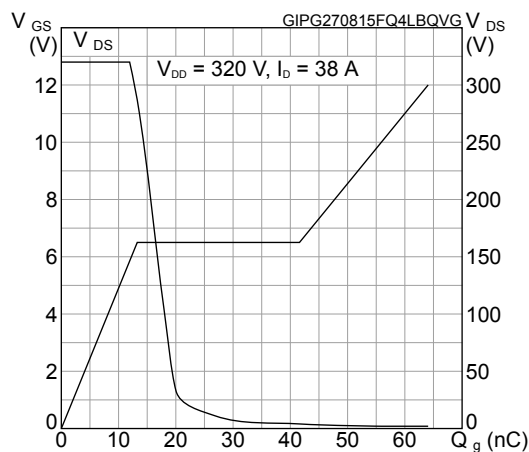
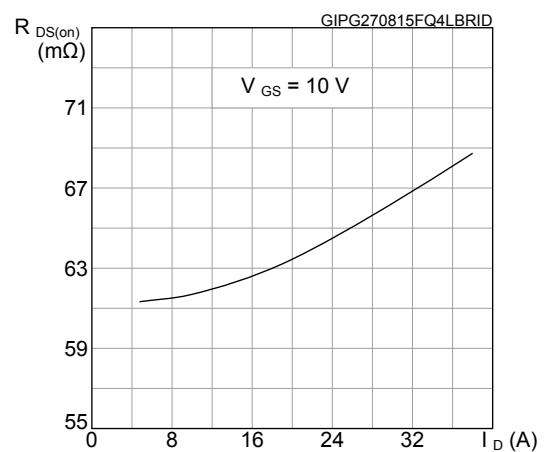
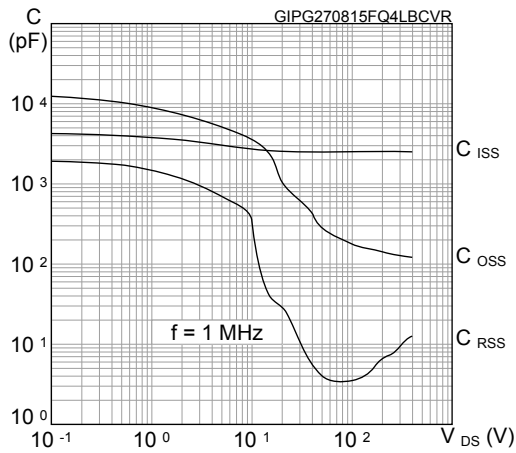


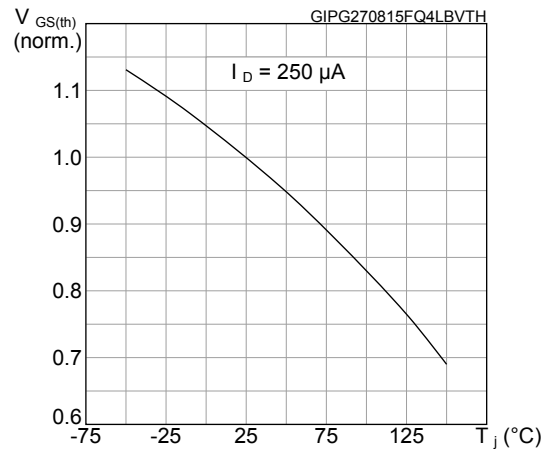
Figure 6. Typical drain-source on-resistance



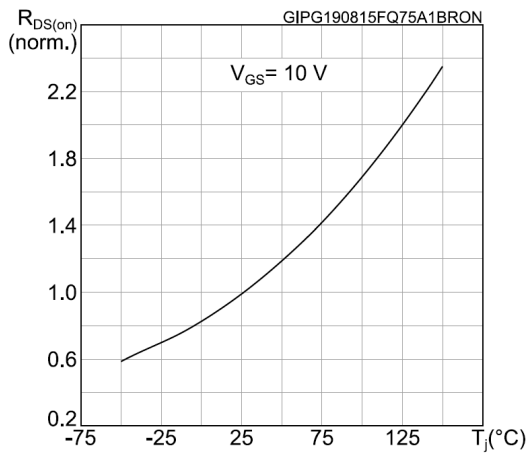
**Figure 7. Typical capacitance characteristics**



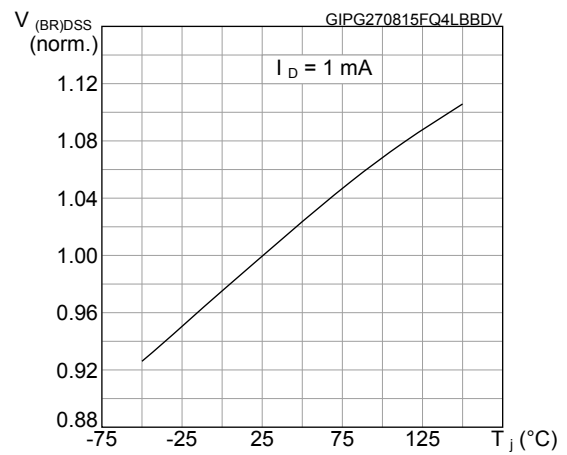
**Figure 8. Normalized gate threshold vs temperature**



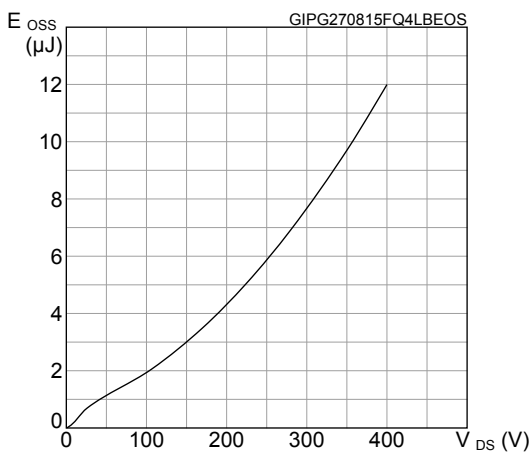
**Figure 9. Normalized on-resistance vs temperature**



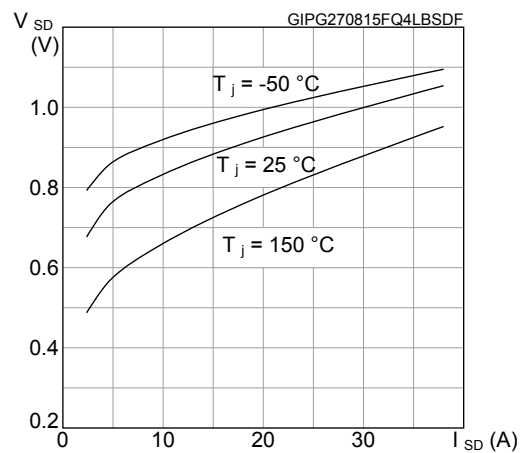
**Figure 10. Normalized breakdown voltage vs temperature**



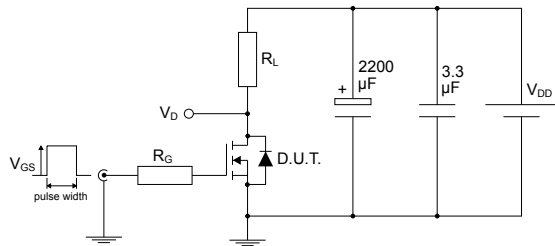
**Figure 11. Typical output capacitance stored energy**



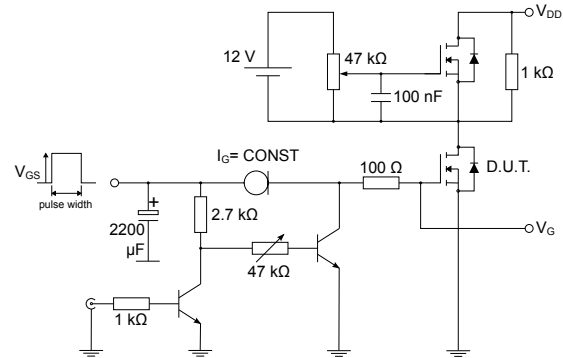
**Figure 12. Typical reverse diode forward characteristics**



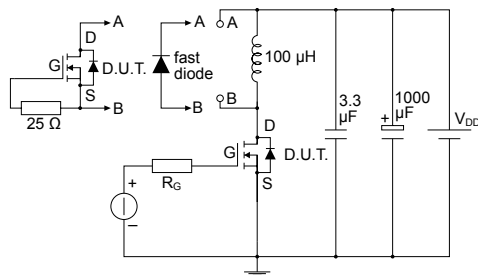
### 3 Test circuits

**Figure 13. Test circuit for resistive load switching times**


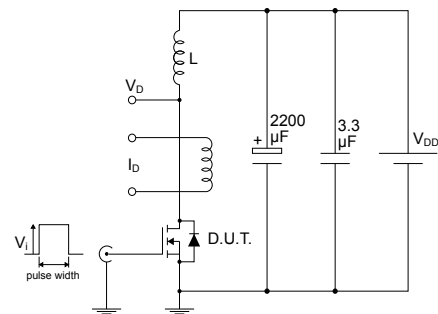
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**Figure 14. Test circuit for gate charge behavior**


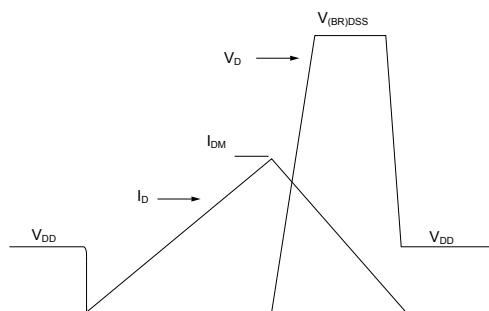
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**Figure 15. Test circuit for inductive load switching and diode recovery times**


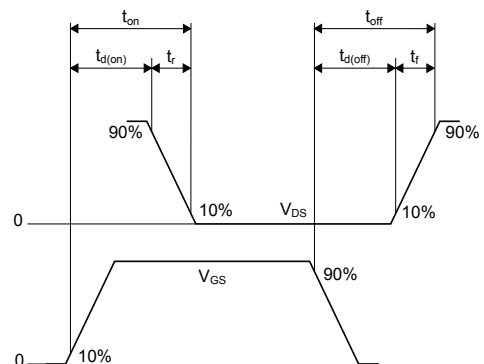
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**Figure 16. Unclamped inductive load test circuit**


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**Figure 17. Unclamped inductive waveform**


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**Figure 18. Switching time waveform**


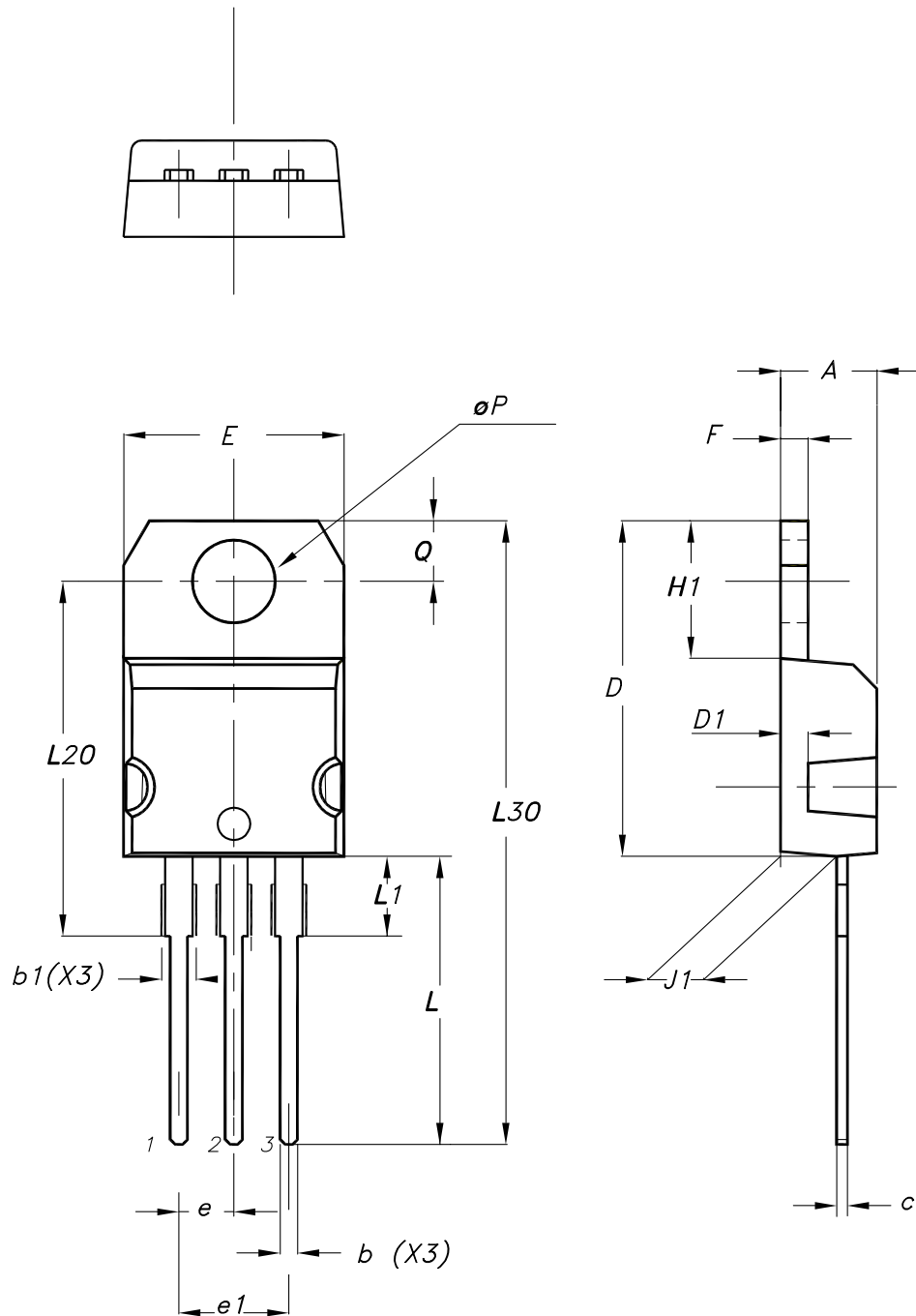
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## 4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-220 type A package information

Figure 19. TO-220 type A package outline



0015988\_typeA\_Rev\_24

**Table 8. TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

## Revision history

**Table 9. Document revision history**

Date	Revision	Changes
06-Jul-2015	1	First release.
03-Sep-2015	2	Datasheet promoted from preliminary data to production data Modified: ID, IDM, dv/dt values in table 2 Added: note 2 and 3 in table2 Modified: the entire values in table 4 Modified: RDS(on) typical value in table 5 Modified: the entire typical values in table 6 and 7 Modified: the entire typical values and ISD, ISDM in table 8 Added: Electrical characteristics (curves) section Minor text changes
02-Aug-2016	3	Modified title in cover page. Updated Section 1: "Electrical ratings", Table 5: "Static", Table 8: "Source-drain diode" and Figure 2: "Safe operating area". Minor text changes.
10-Mar-2026	4	Updated <a href="#">Section 4.1: TO-220 type A package information</a> . Minor text changes.

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